

3310J-VB Datasheet

P-Channel 30-V (D-S) MOSFET

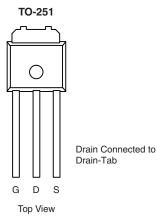
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)		
- 30	0.056at V _{GS} = - 10 V	- 20	19 nC		
- 30	0.072 at V _{GS} = - 4.5 V	- 15	19110		

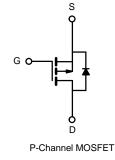
FEATURESHalogen-free

- nalogen-free
- Trench Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- Load Switch
- Notebook Adaptor Switch





Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 30	N	
Gate-Source Voltage		V _{GS}	± 20	V
	T _C = 25 °C		- 20	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 15	
Continuous Drain Current $(T_j = 150^{\circ} C)$	T _A = 25 °C	I _D	-7.9 ^{a, b}	
	T _A = 70 °C		- 5.6 ^{a, b}	•
Pulsed Drain Current		I _{DM}	- 60	— A
Outline Output Date Divide Output	T _C = 25 °C	1	- 20	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 7.9 ^{a, b}	
Avalanche Current	L = 0.1 mH	I _{AS}	- 20	
Single-Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	20	mJ
	T _C = 25 °C		20	
Maximum Dower Dissinction	T _C = 70 °C	P _D	15	w
Maximum Power Dissipation	T _A = 25 °C		2.7 ^{a, b}	vv
	T _A = 70 °C	1	1.7 ^{a, b}	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	46	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	- °C/vv	

Notes:

b. t = 10 s.

c. Maximum under Steady State conditions is 85 $^{\circ}\text{C/W}.$

d. Based on T_C = 25 °C.

a. Surface mounted on 1" x 1" FR4 board.

SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				1			
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 34		mV/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			5.3		°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.4		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 25 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 1 - 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 20			Α	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = - 10 V, I _D = - 6 A V_{GS} = - 4.5 V, I _D = - 4 A		0.056		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6 A		28		S	
Dynamic ^b				1		1	
Input Capacitance	C _{iss}			1150			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		205		pF	
Reverse Transfer Capacitance	C _{rss}			140			
Total Gate Charge		V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 6 A		27	43	nC	
	Q_g			19	25		
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 6 A		6			
Gate-Drain Charge	Q _{gd}			12			
Gate Resistance	R _q	f = 1 MHz	0.5	2.2	4.4	Ω	
Turn-On Delay Time	t _{d(on)}			13	25		
Rise Time	tr	V_{DD} = - 15 V, R _L = 1.5 Ω		12	24	-	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_q = 1 Ω		40	70		
Fall Time	t _f			9	18		
Turn-On Delay Time	t _{d(on)}			48	80	ns	
Rise Time	t _r	V_{DD} = - 15 V, R _L = 1.5 Ω		92	160		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 6 A, V_{GEN} = - 4.5 V, R_q = 1 Ω		34	60		
Fall Time	t _f			19	35		
Drain-Source Body Diode Characteris	stics						
Continous Source-Drain Diode Current	۱ _s	T _C = 25 °C			- 4.1		
Pulse Diode Forward Current	I _{SM}				- 60	A	
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			27	45	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			16	27	nC	
Reverse Recovery Fall Time	t _a	$I_F = -6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12			
Reverse Recovery Rise Time	t _b	1		15		ns	

Notes:

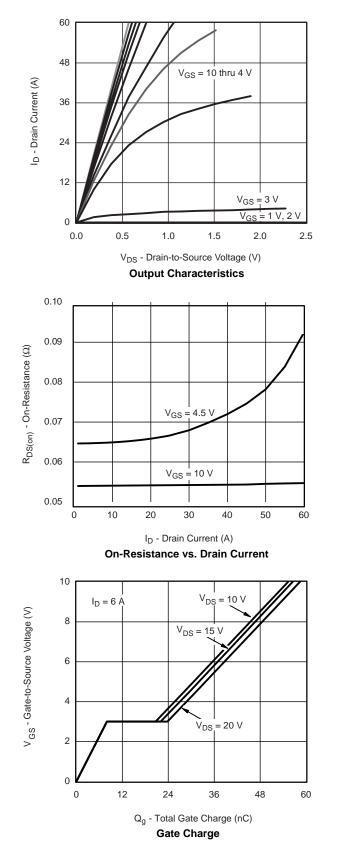
a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

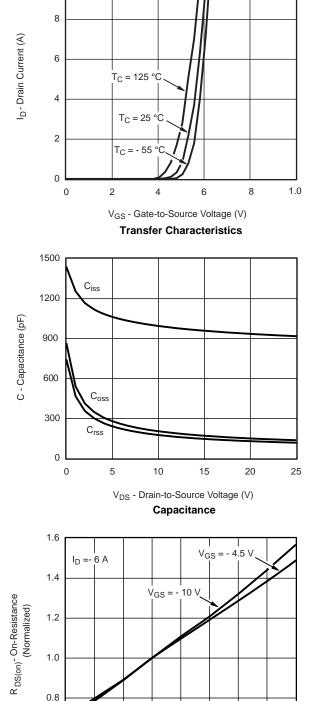
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



10

0.6

- 50

- 25

0

25

50

On-Resistance vs. Junction Temperature

T_J - Junction Temperature (°C)

75

100

125

150



 $I_D = 6 A$

T_J = 25 °C

10

10

8

T_J = 125 °C

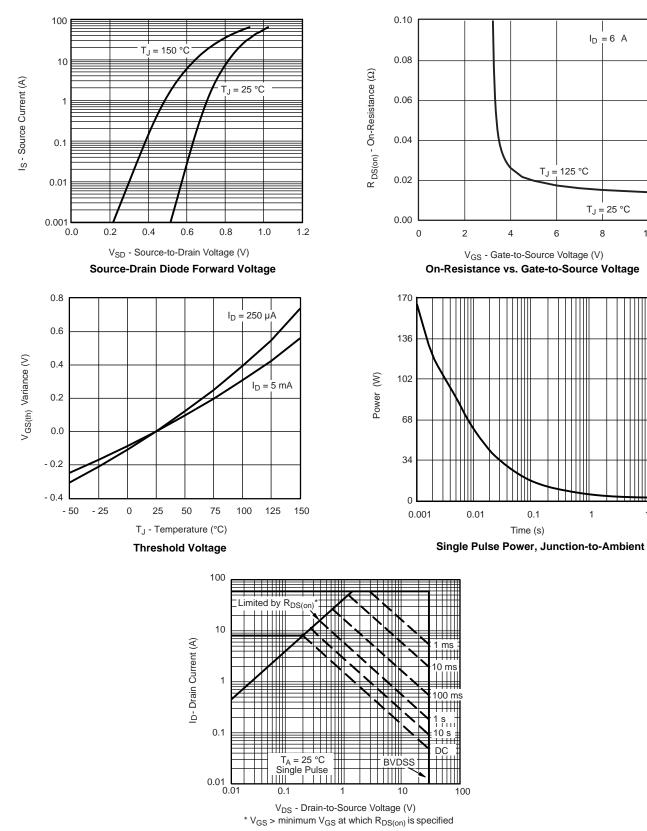
6

4

0.1

Time (s)

1



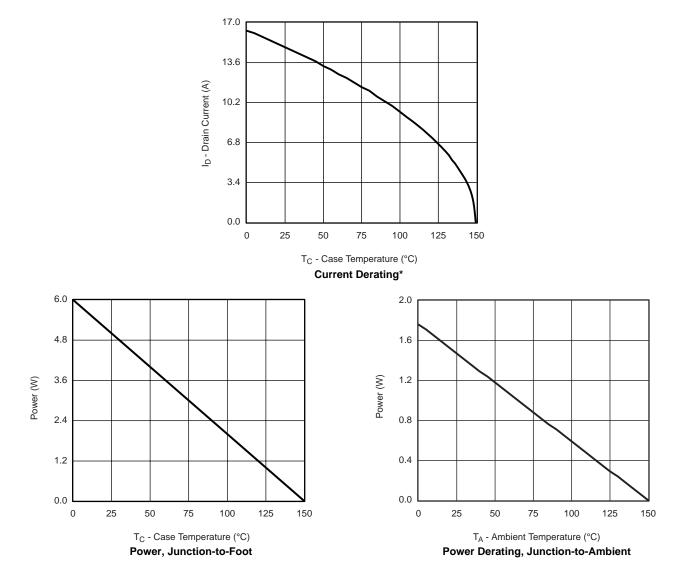
Safe Operating Area

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





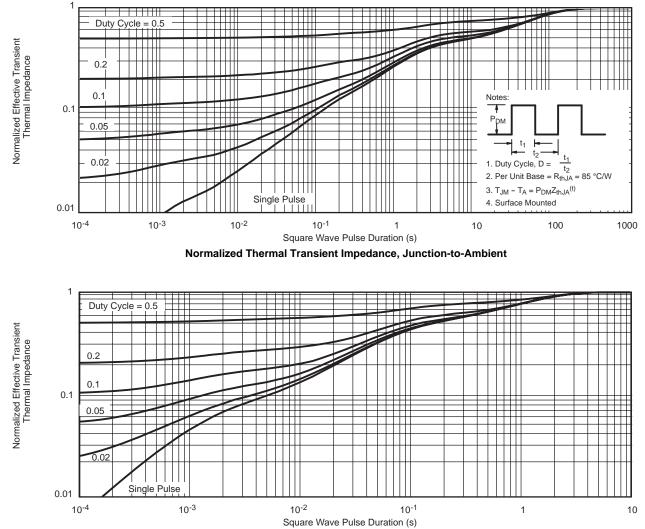
MOSFET TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



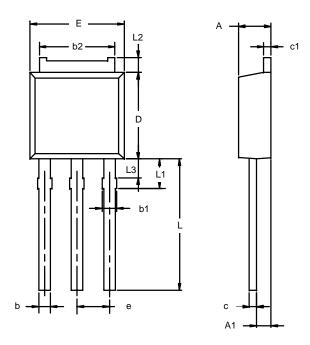
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



TO-251AA



	MILLIM	IETERS	INC	HES
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
Е	6.48	6.73	0.255	0.265
е	2.28	BSC	0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060

Note: Dimension L3 is for reference only.



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